## 1-2198346-7 ACTIVE

TE Internal #: 1-2198346-7

SFP/SFP+/zSFP+, Cage Assembly with Integrated Connector, Data

Rate (Max) 32 Gb/s, Elastomeric Gasket, zSFP+ Thermally

Enhanced, Included Lightpipe

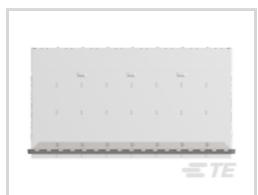
View on TE.com >

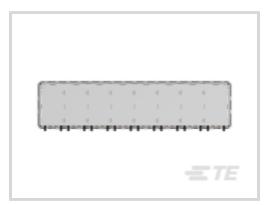


Connectors > Pluggable IO Connectors & Cages > SFP/SFP+/zSFP+ > zSFP+ Stacked Cage Assembly: Gasket











Pluggable I/O Product Type: Cage Assembly with Integrated Connector

Data Rate (Max): 32 Gb/s

EMI Containment Feature Type: Elastomeric Gasket
Pluggable I/O Applications: zSFP+ Thermally Enhanced

Included Lightpipe: Yes

All zSFP+ Stacked Cage Assembly: Gasket (40)

### Features

### **Product Type Features**

| Form Factor                       | zSFP+ Stacked (SFP28)                   |
|-----------------------------------|---|
| Cage Type                         | Stacked                                 |
| Pluggable I/O Product Type        | Cage Assembly with Integrated Connector |
| Integrated Lightpipes             | Yes                                     |
| Connector System                  | Cable-to-Board                          |
| Sealable                          | Yes                                     |
| Connector & Contact Terminates To | Printed Circuit Board                   |

### **Configuration Features**

| Port Matrix Configuration | 2 x 6    |
|---------------------------|----------|
| Lightpipe Configuration   | Three    |
| Lightpipe Style           | Standard |
| Number of Ports           | 12       |
| Number of Positions       | 320      |



### **Electrical Characteristics**

| Electrical Characteristics                  |  |
|---|--|
| Data Rate (Max)                             | 32 Gb/s                                  |
| Contact Features                            |  |
| Tail Plating Material                       | Tin                                      |
| Contact Mating Area Plating Thickness       | .76 μm[29.92 μin]                        |
| Contact Mating Area Plating Material        | Gold or Gold Flash over Palladium Nickel |
| Termination Features                        |  |
| Termination Method to Printed Circuit Board | Through Hole - Press-Fit                 |
| Mechanical Attachment                       |  |
| PCB Mounting Style                          | Through Hole - Press-Fit                 |
| Housing Features                            |  |
| Cage Material                               | Nickel Silver Alloy                      |
| Centerline (Pitch)                          | .8 mm[.032 in]                           |
| Dimensions                                  |  |
| PCB Thickness (Recommended)                 | 1.5 mm[.059 in]                          |
| Tail Length                                 | 1.8 mm[.07 in]                           |
| Usage Conditions                            |  |
| Operating Temperature Range                 | -55 – 105 °C[-67 – 221 °F]               |
| Operation/Application                       |  |
| Heat Sink Compatible                        | No                                       |
| For Use With Pluggable I/O Products         | zSFP+ SMT Connector                      |
| Pluggable I/O Applications                  | zSFP+ Thermally Enhanced                 |
| Circuit Application                         | Signal                                   |
| Industry Standards                          |  |
| UL Flammability Rating                      | UL 94V-0                                 |
| Packaging Features                          |  |
| Packaging Method                            | Tray                                     |
| Other                                       |  |
| EMI Containment Feature Type                | Elastomeric Gasket                       |
| Included Lightpipe                          | Yes                                      |



### **Product Compliance**

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU                  | Compliant  |
|---|--|
| EU ELV Directive 2000/53/EC                   | Compliant  |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                            |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JAN 2021<br>(211)<br>Not Yet Reviewed |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.                     |
| Solder Process Capability                     | Not applicable for solder process capability                       |

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

## **Compatible Parts**













TE Part # CAT-C11-N49011 SFP28 to SFP28 Cable Assembly: 26 AWG



TE Part # CAT-Q17-N49011 QSFP56-Four SFP56 Cable Assembly: 30 AWG



TE Part # CAT-Q17-N490333 QSFP56-Four SFP56 Cable Assembly: 26 AWG



TE Part # CAT-C11-G28037 SFP56 to SFP56 Cable Assembly: 30 AWG



TE Part # CAT-C11-G28 SFP56 to SFP56 Cable Assembly: 26 AWG



TE Part # 2821262-1 SFP28 DIRECT ATTACH CA, 0.5M, 33AWG



TE Part # 4-2334985-2 SFP56 DIRECT ATTACH CA, 1M, 32AWG



TE Part # CAT-C11-N490111 SFP28 to SFP28 Cable Assembly: 28 AWG



TE Part # 2821262-2 SFP28 DIRECT ATTACH CA, 1.0M, 33AWG



TE Part # 2821262-3 SFP28 DIRECT ATTACH CA, 1.5M, 33AWG



TE Part # 2821262-4 SFP28 DIRECT ATTACH CA, 2.0M, 33AWG

# Customers Also Bought



TE Part #2198339-2 zSFP+ Stacked Cage Assembly: Gasket



TE Part #2180324-6 zSFP+ Stacked Cage Assembly: EMI Spring



TE Part #2170704-1 CAGE ASSY, QSFP28 1X1, SPRING, HS



TE Part #2227668-2 zQSFP+ STACKED RECEPTACLE ASSEMBLY 2X3



### **Documents**



### **Product Drawings**

zSFP+ STACKED 2X8 RECEPTACLE ASSEMBLY

English

**CAD Files** 

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_1-2198346-7\_A.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-2198346-7\_A.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-2198346-7\_A.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

### Datasheets & Catalog Pages

zSFP+ Interconnect Brochure

English

### **Product Specifications**

**Application Specification** 

English

### **Instruction Sheets**

Instruction Sheet (U.S.)

English

Instruction Sheet (U.S.)

English